



#### DMN5/L06VK/L06VAK/010VAK

#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

#### **Features**

- **Dual N-Channel MOSFET**
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- ESD Protected up to 2kV
- Qualified to AEC-Q101 standards for High Reliability

#### **Mechanical Data**

- Case: SOT563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.006 grams (approximate)

**SOT563** 

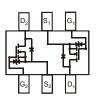






Top View





DMN5L06VAK DMN5010VAK

## **Ordering Information** (Note 4)

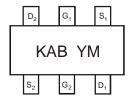
Part Number	Case	Packaging
DMN5L06VK-7	SOT563	3,000/Tape & Reel
DMN5L06VK-13	SOT563	10,000/Tape & Reel
DMN5L06VAK-7	SOT563	3,000/Tape & Reel
DMN5L06VAK-13	SOT563	10,000/Tape & Reel
DMN5010VAK-7	SOT563	3,000/Tape & Reel
DMN5010VAK-13	SOT563	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.
- 5. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

### Marking Information (Note 5)

#### DMN5L06VK



KAB= DMN5L06VK Product Type Marking Code (See Note 4) YM = Date Code Marking

Y = Year (ex: T = 2006)

M = Month (ex: 9 = September)

# G, xxx YM $D_1$

#### DMN5010VAK DMN5L06VAK

xxx = Product Type Marking Code: KAE or KAC (See Note 4) YM = Date Code Marking

Y = Year (ex: T = 2006)

M = Month (ex: 9 = September)

Date Code Key

Date Code IV												
Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	Т	U	V	W	Χ	Υ	Z	Α	В	С	D	Е
										I.	I.	
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain Source Voltage	$V_{DSS}$	50	V	
Drain-Gate Voltage R <sub>GS</sub> ≤ 1.0MΩ		$V_{DGR}$	50	V
Gate-Source Voltage	Continuous Pulsed	$V_{GSS}$	±20 ±40	V
Drain Current (Note 6)	Continuous Pulsed	I <sub>D</sub> I <sub>DM</sub>	280 1.5	mA A

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	$P_{D}$	250	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

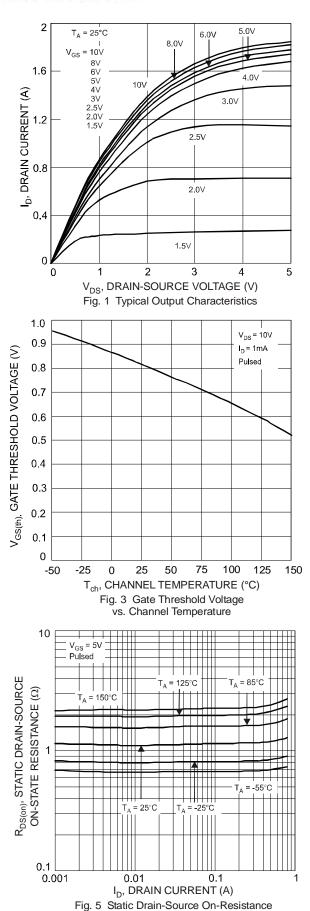
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)								
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	50	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$	
Zero Gate Voltage Drain Current	@ T <sub>C</sub> = +25°C	I <sub>DSS</sub>	_	_	60	nA	$V_{DS} = 50V, V_{GS} = 0V$	
					1	μA	$V_{GS} = \pm 12V, V_{DS} = 0V$	
Gate-Body Leakage		I <sub>GSS</sub>	_	_	500	nA	$V_{GS} = \pm 10V$ , $V_{DS} = 0V$	
					50	nA	$V_{GS} = \pm 5V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)								
Gate Threshold Voltage		V <sub>GS(th)</sub>	0.49	_	1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			_	_	3.0		$V_{GS} = 1.8V, I_D = 50mA$	
Static Drain-Source On-Resistance		R <sub>DS (ON)</sub>	_	_	2.5	Ω	$V_{GS} = 2.5V, I_D = 50mA$	
			_	_	2.0		$V_{GS} = 5.0V, I_D = 50mA$	
On-State Drain Current		I <sub>D(ON)</sub>	0.5	1.4	_	Α	$V_{GS} = 10V, V_{DS} = 7.5V$	
Forward Transconductance		Y <sub>fs</sub>	200	_	_	mS	$V_{DS} = 10V, I_D = 0.2A$	
Source-Drain Diode Forward Voltage		$V_{SD}$	0.5	_	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$	
DYNAMIC CHARACTERISTICS (Note 8)								
Input Capacitance		C <sub>iss</sub>	_		50	pF	\/ 05\/ \/ 0\\	
Output Capacitance		Coss			25	pF	$V_{DS} = 25V, V_{GS} = 0V$ -f = 1.0MHz	
Reverse Transfer Capacitance		C <sub>rss</sub>	_	_	5.0	pF	11 = 1.UIVIMZ	

Notes:

- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.7. Short duration pulse test used to minimize self-heating effect.8. Guaranteed by design. Not subject to product testing.







0.4

V<sub>DS</sub> = 10V
Pulsed

T<sub>A</sub> = 150°C

T<sub>A</sub> = 125°C

T<sub>A</sub> = 85°C

T<sub>A</sub> = -25°C

0.01

0

0.5

1.5

2

V<sub>GS</sub>, GATE-SOURCE VOLTAGE (V)
Fig. 2 Typical Transfer Characteristics

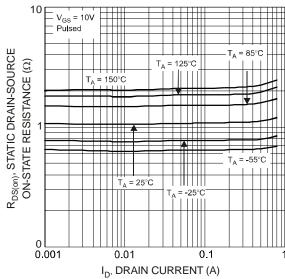
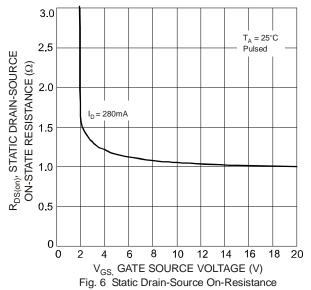


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current



vs. Drain Current



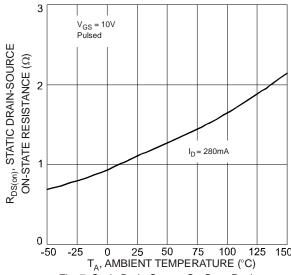
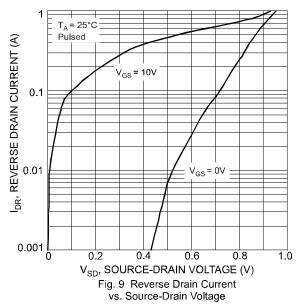
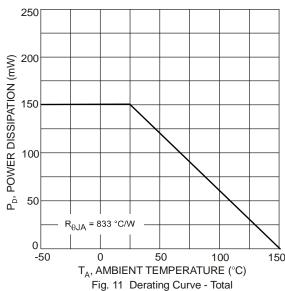


Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature





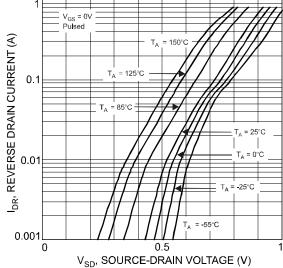


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

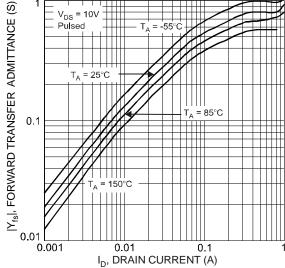
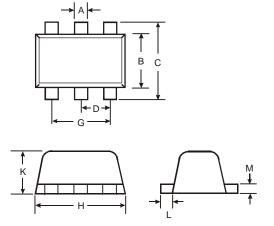


Fig.10 Forward Transfer Admittance vs. Drain Current

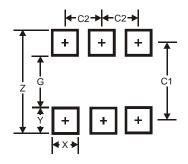


## **Package Outline Dimensions**



SOT563					
Dim	Min	Max	Тур		
Α	0.15	0.30	0.20		
В	1.10	1.25	1.20		
С	1.55	1.70	1.60		
D	-	-	0.50		
G	0.90	1.10	1.00		
Н	1.50	1.70	1.60		
K	0.55	0.60	0.60		
L	0.10	0.30	0.20		
M	0.10	0.18	0.11		
All Dimensions in mm					

## **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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